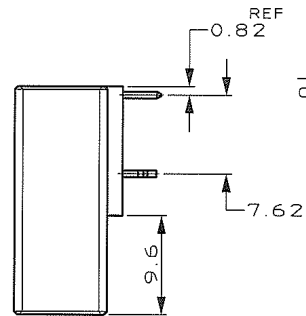
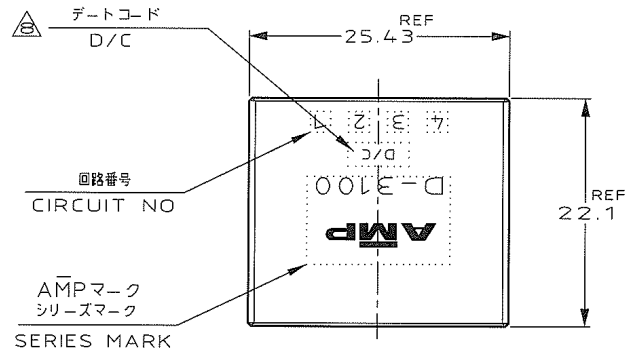


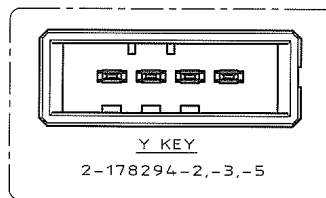
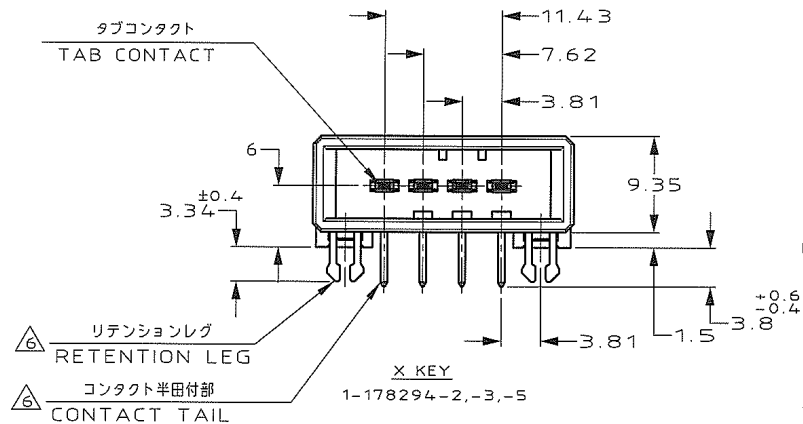
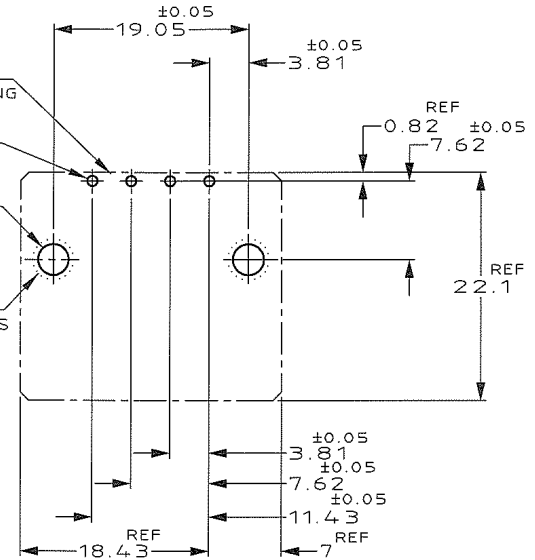


コネクタ外形
OUTLINE OF HEADER HOUSING

4-φ1.1
DIA1.1±0.1 3PLACES

スルーホール 2-φ3
DIA3±0.1 2PLACES

ラウンド 2-φ4MIN
ROUND DIA4MIN 2PLACES



6	4	1,2-178294-5
6	3	1,2-178294-3
6	2	1,2-178294-2
(FINISH)		製品番号 (PART NO.)

NOTES

- MATERIAL:HOUSING:GLASS FILED THERMO
PLASTIC,POLYESTER(94V-0), COLOR: BLACK
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH(CONTACT AREA): 0.38μm PdNi & Au PLATING OVER NICKEL
- FINISH(CONTACT AREA): 0.76μm PdNi & Au PLATING OVER NICKEL
- FINISH(CONTACT AREA): 2.0 μmMIN TIN
PLATED OVER NICKEL
- FINISH(RETENTION LEG): TIN LEAD PLATED
(CONTACT TAIL) OVER NICKEL
- FINISH(RETENTION LEG): TIN PLATED
(CONTACT TAIL) OVER NICKEL
- THE SHAPE,SIZE AND POSITION OF THE
CHARACTER SHOW THE OUTLINE
THEY DON'T SHOW DETAILS
- THE DATE CODE SHOW PRODUCTION LOT BY NUMBER.
THE NUMBER MAKE UP THE NUMBER OF FOUR COLUMNS
OR FIVE COLUMNS. (INCLUDE THE ALPHABET)

推奨基板取付け寸法

PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

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B3	REVISED	PER ECR-25-250788	F.Z.	R.B.	16JAN 2025	WIRE RANGE		INSULATION DIA	NAME		
B3	REVISED		H.O.	N.Y.	14NOV 2014	mm(AWG -)		mmZ	ダイナミック 3100 シリーズ 4極 ヘッダーアセンブリー (水平タイプ) 4 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC 3100		
B2	REVISED		Y.O.	T.K.	7 OCT 2002	MATERIAL		FINISH	一般公差 (GENERAL TOLERANCE)		
B1	REVISED	ECR-08-029637	T.S.	A.O.	21NOV 2008	SEE NOTE 注記参照		SEE NOTE 注記参照	SIZE LOC NUMBER		
B	REVISED	(FJD0-0039-03)	T.S.	S.M.	23JUN '03	DR.		DE.	A3 J C-178294		
A	REVISED	(FJD0-0114-03)	T.S.	S.M.	25APR '03	CHK.		APP.	SCALE 2-1 REV. C SHEET 1 OF 1		
O	RELEASED	(FJD0-1468-94)	K.I.	S.M.	1-10 '95	DR.		DE.			
LTR	REVISION RECORD		DR	CHK	DATE	S. MANABE		S. MANABE			